STPS30H100DJF

## Power Schottky rectifier

## Datasheet - production data

## Features

- Very low conduction losses
- Low forward voltage drop

■ Low thermal resistance

- High specified avalanche capability
- High integration
- ECOPACK ${ }^{\circledR} 2$ compliant component


## Description

The STPS30H100DJF is a power Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.
Housed in a PowerFLAT ${ }^{\text {TM }}$ package, this device is intended to be used in adaptors requiring good efficiency at both low and high load. Its low profile was especially designed to be used in applications with space-saving constraints.


Table 1. Device summary

| Symbol | Value |
| :---: | :---: |
| $\mathrm{I}_{\mathrm{F}(\mathrm{AV})}$ | 30 A |
| $\mathrm{~V}_{\mathrm{RRM}}$ | 100 V |
| $\mathrm{~T}_{\mathrm{j}}$ | $150^{\circ} \mathrm{C}$ |
| $\mathrm{V}_{\mathrm{F}}(\mathrm{typ})$ | 0.56 V |

## Characteristics

Table 2. Absolute ratings (limiting values, anode terminals short circuited)

| Symbol | Parameter | Value | Unit |  |
| :---: | :--- | :---: | :---: | :---: |
| $\mathrm{V}_{\mathrm{RRM}}$ | Repetitive peak reverse voltage | 100 | V |  |
| $\mathrm{I}_{\mathrm{F}(\mathrm{RMS})}$ | Forward rms current | 45 | A |  |
| $\mathrm{I}_{\mathrm{F}(\mathrm{AV})}$ | Average forward current $\delta=0.5$ | $\mathrm{~T}_{\mathrm{C}}=100^{\circ} \mathrm{C}$ | 30 | A |
| $\mathrm{I}_{\mathrm{FSM}}$ | Surge non repetitive forward current | $\mathrm{t}_{\mathrm{p}}=10 \mathrm{~ms}$ sinusoidal | 250 | A |
| $\mathrm{P}_{\text {ARM }}$ | Repetitive peak avalanche power | $\mathrm{t}_{\mathrm{p}}=1 \mu \mathrm{~s}, \mathrm{~T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ | 3700 | W |
| $\mathrm{~V}_{\text {ARM }}$ | Maximum repetitive peak avalanche <br> voltage | $\mathrm{t}_{\mathrm{p}}<1 \mu \mathrm{~s}, \mathrm{~T}_{\mathrm{j}}<150^{\circ} \mathrm{C}$ <br> $\mathrm{I}_{\mathrm{AR}}<9.3 \mathrm{~A}$ | 120 | V |
| $\mathrm{~T}_{\text {stg }}$ | Storage temperature range |  | -65 to +175 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{j}}$ | Maximum operating junction temperature ${ }^{(1)}$ | 150 | ${ }^{\circ} \mathrm{C}$ |  |

1. $\frac{\mathrm{dPtot}}{\mathrm{dTj}}<\frac{1}{\mathrm{Rth}(\mathrm{j}-\mathrm{a})}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

| Symbol | Parameter | Value | Unit |
| :---: | :--- | :---: | :---: |
| $\mathrm{R}_{\mathrm{th}(\mathrm{j}-\mathrm{c})}$ | Junction to case | 2 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |

Table 4. Static electrical characteristics (anode terminals short circuited)

| Symbol | Parameter | Test conditions |  | Min. | Typ. | Max. | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $I_{R}{ }^{(1)}$ | Reverse leakage current | $\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ | $\mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\text {RRM }}$ | - | - | 6 | $\mu \mathrm{A}$ |
|  |  | $\mathrm{T}_{\mathrm{j}}=125^{\circ} \mathrm{C}$ |  | - | 2.5 | 6.5 | mA |
| $\mathrm{V}_{\mathrm{F}}{ }^{(1)}$ | Forward voltage drop | $\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ | $\mathrm{I}_{\mathrm{F}}=15 \mathrm{~A}$ | - | - | 0.76 | V |
|  |  | $\mathrm{T}_{\mathrm{j}}=125^{\circ} \mathrm{C}$ |  | - | 0.56 | 0.62 |  |
|  |  | $\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ | $\mathrm{I}_{\mathrm{F}}=30 \mathrm{~A}$ | - | - | 0.84 |  |
|  |  | $\mathrm{T}_{\mathrm{j}}=125^{\circ} \mathrm{C}$ |  | - | 0.63 | 0.71 |  |

1. Pulse test: $\mathrm{t}_{\mathrm{p}}=380 \mu \mathrm{~s}, \delta<2 \%$

To evaluate the conduction losses use the following equation:
$P=0.60 \times \mathrm{I}_{\mathrm{F}(\mathrm{AV})}+0.00367 \times \mathrm{I}_{\mathrm{F}}{ }^{2}(\mathrm{RMS})$

Figure 1. Average forward power dissipation Figure 2. Average forward current versus versus average forward current


Figure 3. Relative variation of thermal impedance junction to case versus pulse duration


Figure 4. Reverse leakage current versus reverse voltage applied (typical values)

Figure 5. Junction capacitance versus reverse voltage applied (typical values)


Figure 7. Thermal resistance junction to ambient versus copper surface under tab


## 2 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK ${ }^{\circledR}$ packages, depending on their level of environmental compliance. ECOPACK ${ }^{\circledR}$ specifications, grade definitions and product status are available at: www.st.com. ECOPACK ${ }^{\circledR}$ is an ST trademark.

Table 5. PowerFLAT $5 \times 6$ dimensions

|  |  | Dimensions |  |  |  |  |  |  |  |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Millimeters |  |  |  |  |  |  |  |  |  |  |  |  |  |
|  |  |  |  |  |  |  |  |  |  | Min. | Typ. | Max. | Min. | Typ. | Max. |
|  |  |  |  |  |  |  |  |  | A | 0.80 |  | 1.00 | 0.031 |  | 0.039 |
|  |  |  |  |  |  |  |  |  | A1 | 0.02 |  | 0.05 | 0.001 |  | 0.002 |
|  |  |  |  |  |  |  |  |  | A2 |  | 0.25 |  |  | 0.010 |  |
|  |  |  |  |  |  |  |  |  | b | 0.30 |  | 0.50 | 0.012 |  | 0.020 |
|  |  |  |  |  |  |  |  |  | D |  | 5.20 |  |  | 0.205 |  |
|  |  |  |  |  |  |  |  |  | D2 | 4.11 |  | 4.31 | 0.162 |  | 0.170 |
|  |  |  |  |  |  |  |  |  | e |  | 1.27 |  |  | 0.050 |  |
|  |  |  |  |  |  |  |  |  | E |  | 6.15 |  |  | 0.242 |  |
|  |  |  |  |  |  |  |  |  | E2 | 3.50 |  | 3.70 | 0.138 |  | 0.146 |
|  |  |  |  |  |  |  |  |  | L | 0.50 |  | 0.80 | 0.020 |  | 0.031 |
|  |  |  |  |  |  |  |  |  | K | 1.275 |  | 1.575 | 0.050 |  | 0.062 |

Figure 8. Footprint (dimensions in mm )


Figure 9. Tape and reel specifications


## 3 Ordering information

Table 6. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
| :---: | :---: | :---: | :---: | :---: | :---: |
| STPS30H100DJF-TR | PS30 H100 | PowerFLAT $5 \times 6$ | 95 mg | 3000 | Tape and reel |

## 4 Revision history

Table 7. Document revision history

| Date | Revision | Changes |
| :---: | :---: | :--- |
| 29-Mar-2012 | 1 | Initial release. |

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